

Listing of the Claims:

Without prejudice, this listing of the claims replaces all prior versions and listings of the claims in the present application:

Listing of Claims:

1. (Previously Presented) A method for producing a conductive layered coating on an insulating substrate, comprising:

equipping, in selected regions, at least one surface of an electrically insulating substrate with a coating of an electrically highly conductive first metal, the coating being structured as conductor paths;

cleaning the at least one coated surface;

seeding the coating with seeds of a second metal;

depositing a layer including an alloy of the second metal onto the coating seeded with the seeds of the second metal;

firing the substrate deposited with the layer of the second metal to form the conductive layered coating, the firing being performed at a temperature below the melting point of the first metal, the second metal and the alloy; and

contacting a gold bonding wire to the conductive layered coating, wherein:

the substrate includes an LTCC,

the first metal includes silver, and

the second metal includes palladium.

2. (Canceled).

3. (Canceled).

4. (Previously Presented) The method as recited in Claim 1, wherein:

in the depositing of the layer of the second metal, palladium is deposited at a ratio of from 0.1 to 50% percent by weight of the alloy.

5. (Previously Presented) The method as recited in Claim 1, wherein:

in the depositing of palladium, the palladium is deposited in such a way that a concentration of greater than 20% percent by weight palladium in the alloy results.

6. (Original) The method as recited in Claim 1, wherein:

the seeding and the depositing are performed according to an electroless procedure.

7. (Original) The method as recited in Claim 1, wherein:

the firing is performed at a temperature between 830 and 870°C.

8. (Original) The method as recited in Claim 1, wherein:

the firing is performed at a temperature of 850°C.

9 -10. (Canceled).

11. (Previously Presented) A method for producing a conductive layered coating on an electrically insulating substrate, comprising:

equipping, in selected regions, at least one surface of the electrically insulating substrate with a coating of a first metal structured as a conductor path;

cleaning the at least one coated surface;

seeding the at least one coated surface with seeds of a second metal;

depositing a layer including an alloy of the second metal onto the at least one seeded coated surface; and

firing the substrate deposited with the layer to form the conductive layered coating, the firing being performed at a temperature below the melting point of the first metal, the second metal and the alloy.

12. (Currently Amended) The method of claim 11, wherein the substrate includes an LTCC;

13. (Currently Amended) The method of claim 12, wherein the first metal includes silver and the second metal includes palladium.

14. (Previously Presented) The method of claim 13, further comprising:
contacting a gold bonding wire to the conductive coating.